

IN THE CLAIMS

A complete set of the existing claims are set forth below, with the amended claims showing deletions (strikethrough) and insertions (underline).

1. (Currently amended) A photonic package comprising:

a housing;

a semiconductor light source disposed within the housing, the semiconductor light source having a first output and a second output;

a reflective surface disposed inside the housing selected from one of a side wall of the housing and an interior surface of a cover of the housing to reflect said second output; and

a photodetector disposed within the housing adapted to indirectly receive said second output of the semiconductor light source reflected off said reflective surface.
2. (Original) The photonic package of claim 1, wherein the photonic package comprises an optical transponder.
3. (Original) The photonic package of claim 1, wherein the reflective surface comprises an exterior surface of an elevated substrate angularly disposed relative to the second output, to reflect said second output to said photodetector.
4. (Original) The photonic package of claim 1, wherein the photonic package further comprises a reflective mirror to angularly reflect the second output.

5. (Currently amended) The photonic package of claim 4, wherein the reflective surface ~~comprises a side wall of the housing~~ is optically coupled to said reflective mirror to further reflect the second output to said photodetector.

6. (Cancelled)

7. (Original) The photonic package of claim 1, wherein the first output is provided from a front facet of the semiconductor light source.

8. (Original) The photonic package of claim 1, wherein the second output is provided from a back facet of the semiconductor light source.

9. (Original) he photonic package of claim 1, wherein the photodetector comprises a photodiode.

10. (Original) The photonic package of claim 9, wherein the photodiode comprises a p-i-n junction photodiode.

11. (Original) The photonic package of claim 1 further said reflective surface comprises a reflective coating.

12. (Original) The photonic package of claim 11, wherein the reflective coating comprises paint having a pigment of titanium dioxide.

13. (Cancelled)

14. (Cancelled)

15. (Currently amended) The photonic package of claim 1 further comprising a second reflective surface to deflect the second output to the interior surface.

16. (Currently amended) A method for forming a photonic package comprising:
providing a semiconductor light source to provide a first and a second output;
providing a reflective surface to reflect the second output of the semiconductor light source, wherein said providing of a reflective surface comprises providing a reflective interior surface to a housing of the photonic package; and

adapting a photodetector to indirectly receive the second output of the semiconductor light source reflected from the interior surface.

17. (Cancelled)

18. (Cancelled)

19. (Original) The method of claim 16, wherein said providing of a reflective surface comprises providing a substrate having an angular exterior surface, and the method further comprises disposing said substrate in a manner such that said angular exterior surface of

the substrate reflects said second output of the semiconductor light source to said photodetector.

20. (Currently amended) The method of claim 16, ~~wherein said providing of a reflective surface comprises providing a reflective interior surface to a housing of the photonic package, and the method~~ further comprises providing the photonic package with a reflective mirror and disposing said reflective mirror in a manner such that said reflective mirror reflects said second output of the semiconductor light source to said reflective interior surface of the house, for reflection to said photodetector.